

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DONALD R. MULLEN	09/13/2004
MING LI	09/13/2004
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Rambus Inc.
<b>Street Address:</b>	1050 Enterprise Way, Suite 700
<b>City:</b>	Sunnyvale
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	94089
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	8039952
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	MARS - RA365.C1.US
<b>NAME OF SUBMITTER:</b>	TARISA WAIN
<b>SIGNATURE:</b>	/Tarisa Wain/
<b>DATE SIGNED:</b>	05/09/2014
<b>Total Attachments: 1</b>	
source=RA365.P.US Assignment#page1.tif	

ASSIGNMENT

WHEREAS, WE, Donald R. Mullen and Ming Li, ASSIGNORS, citizens of the United States, residing at Mountain View, California and Fremont, California, respectively, are the inventors of the invention in SYSTEM AND METHOD FOR DISSIPATING HEAT FROM A SEMICONDUCTOR MODULE for which we have executed an application for a Patent of the United States

- which is executed on even date herewith or
which was filed on July 8, 2004, Application No. 10/888,907, and identified by Morgan, Lewis & Bockius LLP docket no. 060809-S011-US

and WHEREAS, RAMBUS INC., a Delaware Corporation, having a place of business at 4440 El Camino Real, Los Altos, CA 94022, ASSIGNEE is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

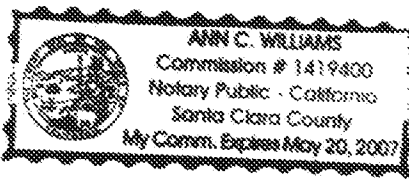
IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

Date 13. Sep 04 2004 Donald R. Mullen L.S.
Date 9-13 2004 Ming Li L.S.

State of California )
County of Santa Clara ) SS.

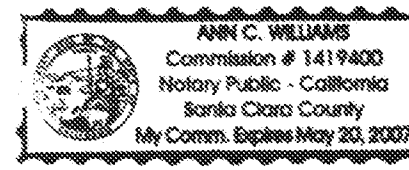
On 9/13 2004, before me, Ann C. Williams, Notary Public, personally appeared Donald R. Mullen, personally known to me on the basis of satisfactory evidence to be the person(s) whose name(s) is subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

WITNESS my hand and official seal
Ann C. Williams
State of California )
County of Santa Clara ) SS.



On 9/13 2004, before me, Ann C. Williams, Notary Public, personally appeared Ming Li, personally known to me on the basis of satisfactory evidence to be the person(s) whose name(s) is subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

WITNESS my hand and official seal
Ann C. Williams



PATENT 83.1 RA365